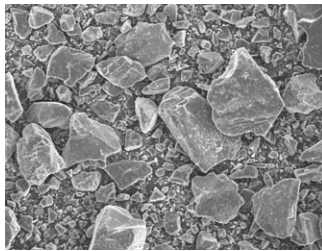


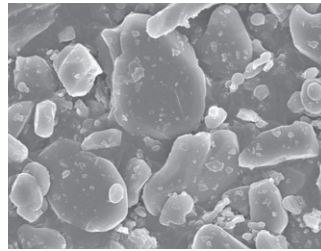
# Filler Alumina

Alumina provides good electronic insulation and thermal conductivity suitable for use in fillers for heat dissipation materials and mold compounds for packages. Various

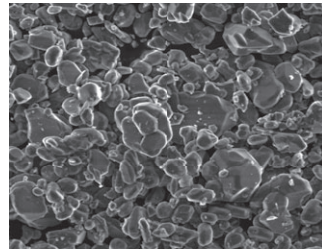
products are available with controlled particle shapes, particle size distribution and purity.



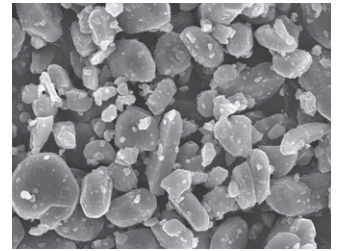
V325F



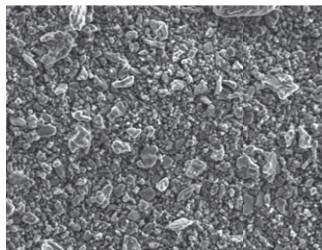
SA34



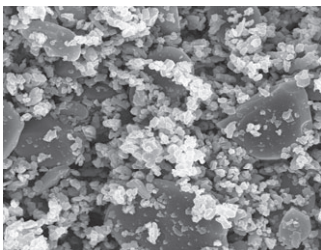
LS-130



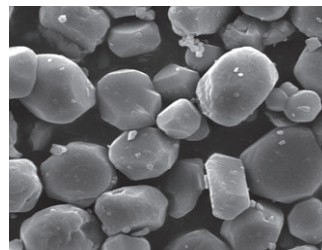
LS-210B



LS-710C



LS-243NM

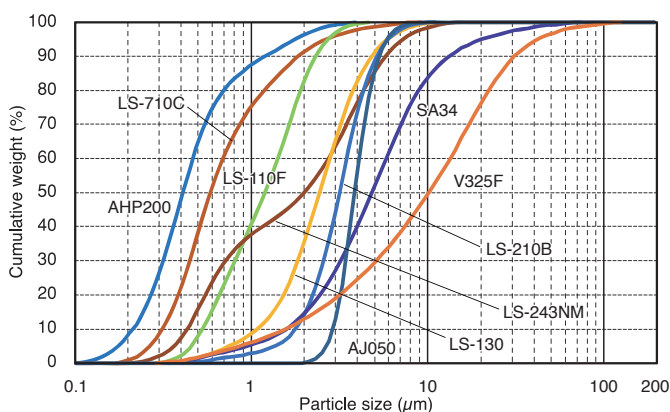


AJ050

## Typical Properties

Grade	V325F	SA34	LS-110F	LS-130	LS-210B	LS-710C	LS-243NM	AJ050	AHP200
LOI (%)	0.04	0.02	0.08	0.02	0.04	0.32	0.05	0.04	0.11
Na <sub>2</sub> O (%)	0.11	0.37	0.03	0.02	0.07	0.08	0.08	0.01	Na 20 ppm
SiO <sub>2</sub> (%)	0.11	0.03	0.07	0.06	0.03	0.02	0.03	0.10	Si 10 ppm
Fe <sub>2</sub> O <sub>3</sub> (%)	0.03	0.02	0.03	0.03	0.02	0.02	0.02	0.02	Fe 2 ppm
Al <sub>2</sub> O <sub>3</sub> (%)	99.7	99.6	99.9	99.9	99.9	99.9	99.9	99.8	99.99
Ave. Particle Size (µm)	12	4.8	1.2	2.4	3.1	0.6	2.0	3.9	0.4
α-Crystal Size (µm)	—	3~7	1~2	2~4	3~5	0.5	0.5~5.0	3~5	0.2~0.4
BET Specific Surface Area (m <sup>2</sup> /g)	1.2	1.9	3.1	1.4	1.4	5.7	3.3	0.9	6.0
Oil Absorption (mℓ/100g)	16	27	26	28	20	26	21	16	30
pH	9	10	9	9	9	10	10	9	6

## Particle Size Distribution



## Applications

- (1) Thermal conductive materials
- (2) Molding compounds for packages
- (3) Compounds

## Packing

Flexible container bag  
Paper bag